

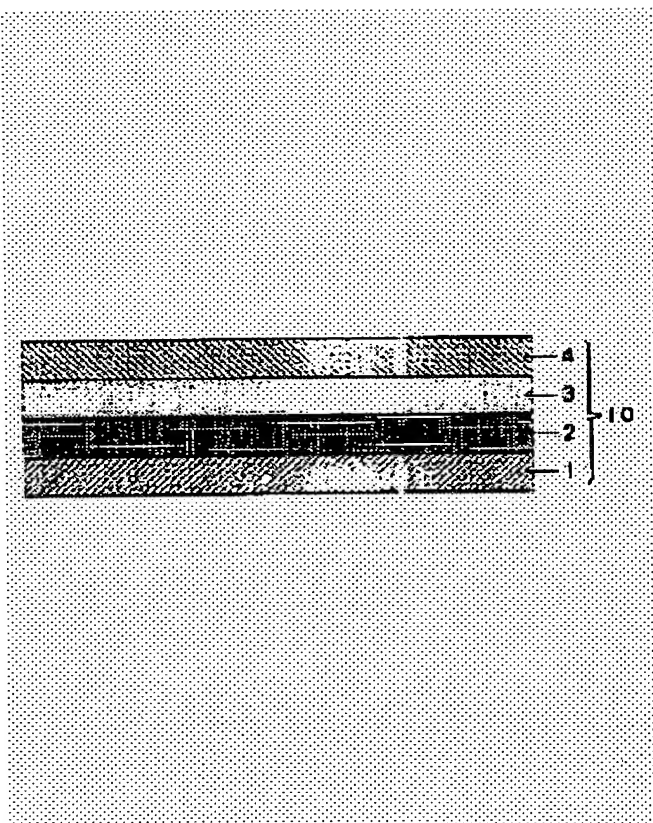
**DRY FILM RESIST HAVING MULTILAYER STRUCTURE**

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- international: G03F7/004; G03F7/11; H01L21/027; H05K3/06  
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**Abstract of JP11015150**

**PROBLEM TO BE SOLVED:** To provide the multilayer dry film resist preventing occurrence of microair in the dry film resist at the time of laminating the resist on a metal substrate and having good dry etching characteristics.

**SOLUTION:** This dry film resist is formed by laminating on a support 1 a nonphotoreactive overcoat layer 2 and a photosensitive layer 3 composed of a photoreactive and a protective layer 4. The nonphotoreactive overcoat layer 2 has a film thickness of  $\geq 10 \mu\text{m}$  and the resist films comprising this overcoat layer 2 and the photosensitive layer 3 composed of the photoreactive composition has a total film thickness of  $\geq 30 \mu\text{m}$ .



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